SUSS
Investor Presentation



mwb Round Table
August 11, 2026

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Company Overview



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SUSS at a glance

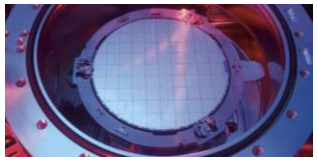
- Hidden champion headquartered in Germany with 75+ years track record of innovation and growth
- Key technology provider for semiconductor frontend and advanced backend industry, benefiting from structural growth drivers such as Artificial Intelligence
- Global customer base with largest share of business in Asia
- Strategic partner for global semiconductor IDMs and foundries
- Innovator with relevant network to research institutes and universities

SUSS is part of our digital life!

Milestones in our company's history



1949
Company founded as Karl Süss KG in Munich



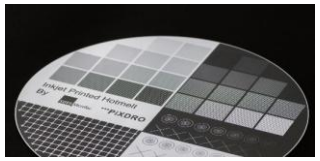
1990
Volume production of wafer bonder starts



2000
Coating systems added through acquisition of Fair-child Technologies

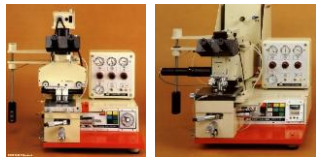


2010
Second German site established after acquisition of Hamatech APE



2020
Inkjet printing added to coating expertise through acquisition of PiXDRO

2024
Relaunch of the brand as SUSS



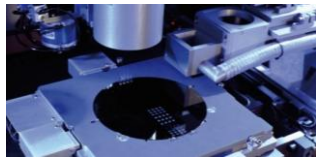
1963
World's first mask aligner SUSS MJB3 developed



1999
Initial Public Offering at the Frankfurt Stock Exchange completed



2001
Company renamed to SUSS MicroTec



2012
Laser processing technology taken over from newly acquired Tamarack Scientific



2020
Asian production site opened in Hsinchu/ Taiwan



2025
Opening of new and larger site in Zhubei/Taiwan

Company Milestones Technology Milestones

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Management Board of SUSS MicroTec SE



CFO

Dr. Cornelia Ballwiesser

- Finance & Controlling
- Legal & Compliance
- Risk Management
- Investor Relations
- IT
- ESG



CEO

Burkhardt Frick

- Sales and Service
- Strategy
- HR
- Internal Audit
- Business Units:
  Advanced Backend Solutions,
  Photomask Solutions



COO

Dr. Thomas Rohe

- R&D
- Purchasing
- Production
- Logistics
- Quality Management
- Facility Management

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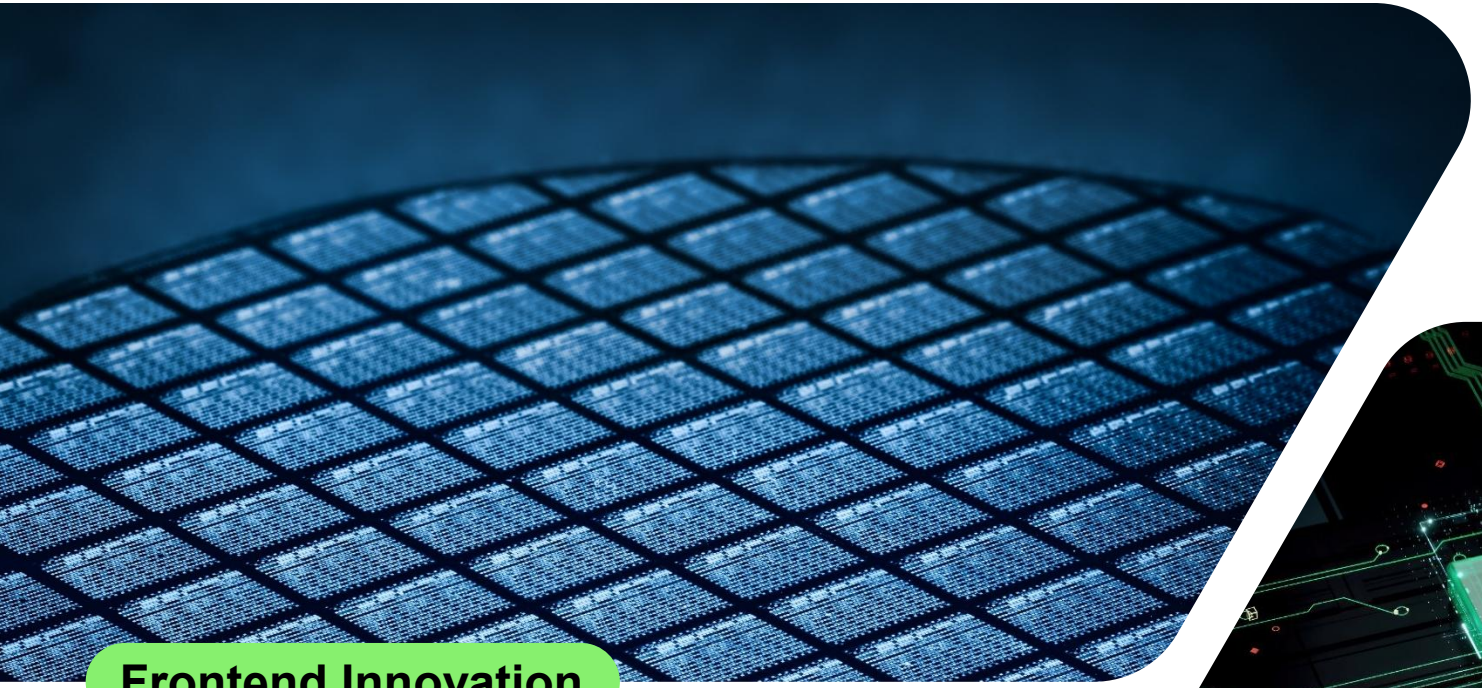
We are fully committed to driving the next chapter of innovation and growth in frontend (Moore's Law) and backend (More than Moore)

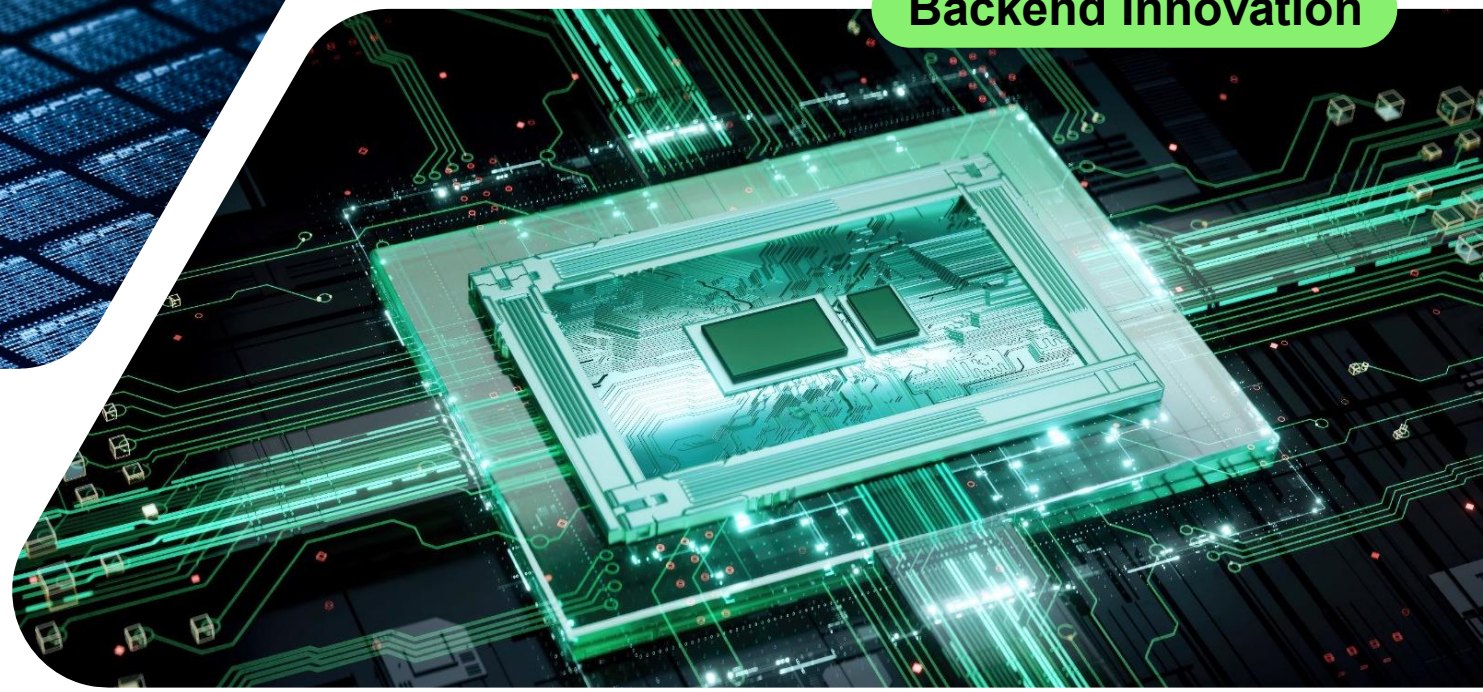


Frontend Innovation

Striving for the next technology node

Heterogeneous integration creates new multi-chip modules

Backend Innovation



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Our two segments, mainly serving the semiconductor industry

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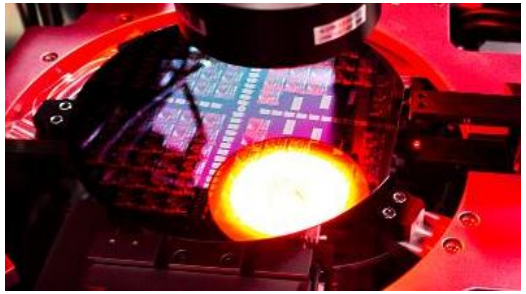
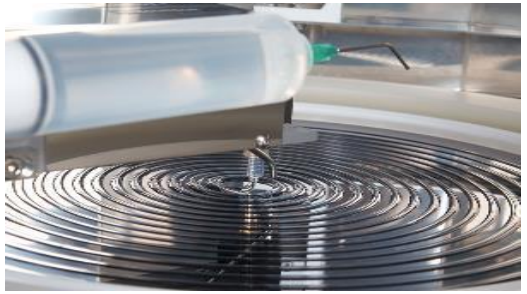
	Frontend	Advanced Backend		
Segments	Photomask Solutions	Advanced Backend Solutions		
				
Products	**Photomask Equipment**  MaskTrack X	**Imaging** Mask Aligner MA200/300   UV Projection Scanner DSC300	**Coating**  ACS300	**Bonding** XBC300   XBC300 Gen2 D2W

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The new application center: a strategic investment into innovation and future growth

Located in Karlsruhe, close to the KIT-Campus, SUSS will invest €45 million until 2028.



First rendering of the planned application and development center in Karlsruhe. The illustration is subject to change as planning progresses.

Innovation Hub:

- Access to key talents and leading semiconductor research through professorship at KIT
- Accelerates product development and innovation cycles
  Strengthens long-term technology leadership

Capacity for Growth:

- Relocation of R&D and application activities to Karlsruhe
- Frees up cleanroom space in Sternenfels

Platform for the Future:

- Improves collaboration between development and customers
- Enables long-term growth in Advanced Packaging

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Financials H1 2026



H1 2026 at a glance:
Record Order Intake of 410.0 million in the first six months

Financial Results

H1 2026

Order Intake

410.0
in € million
+145.8% YoY

Sales

202.8
in € million
-23.9% YoY

Gross Profit Margin

37.2
in %
-0.8 % YoY

EBIT Margin

7.0
in %
-9.5 pp YoY

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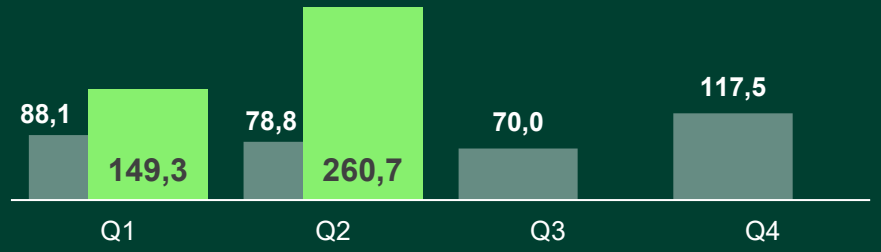
Q2 2026 delivered significantly higher sales and profitability than Q1

Group

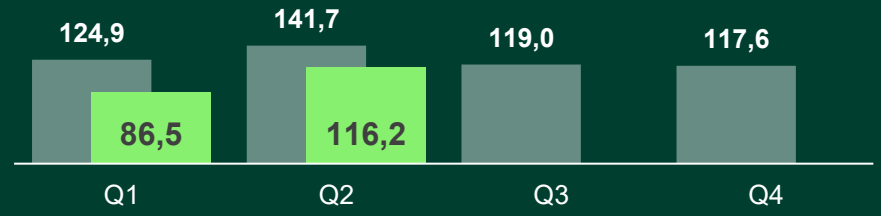
Order intake
(Q2 2026)

€260.7m



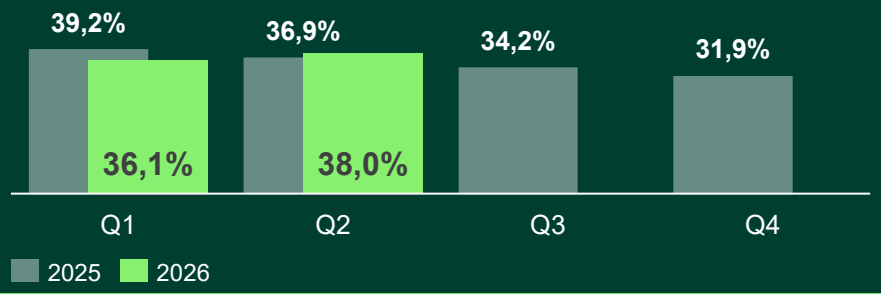
Sales
(Q2 2026)

€116.2m



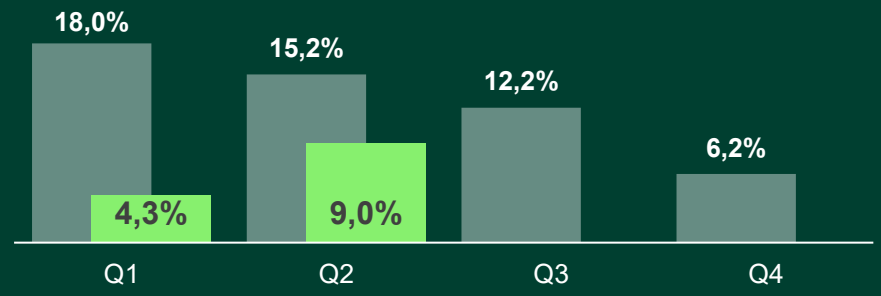
Gross profit margin

38.0% (Q2 2026)



EBIT margin

9.0% (Q2 2026)



The prior-year figures have been adjusted.

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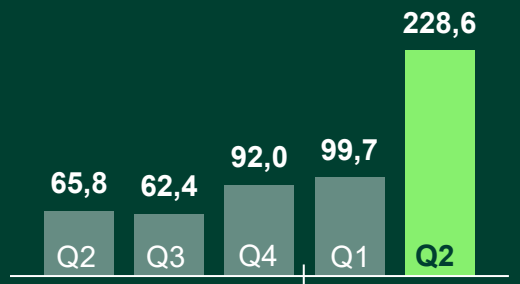
Strong order intake and rising sales in Advanced Backend Solutions

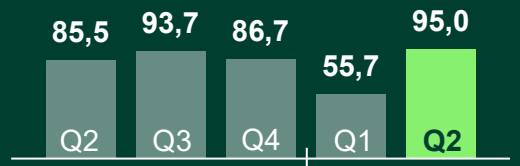
Segments

Advanced Backend Solutions

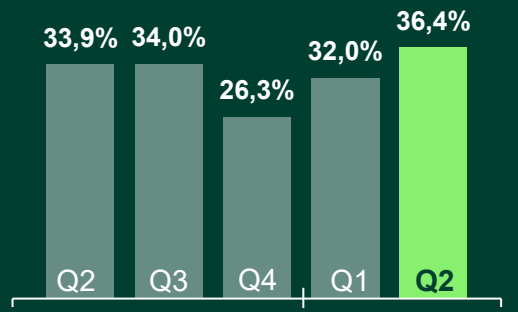
Order intake by quarters



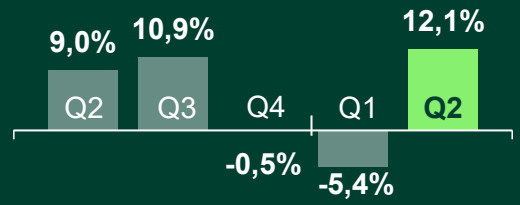
Sales by quarters



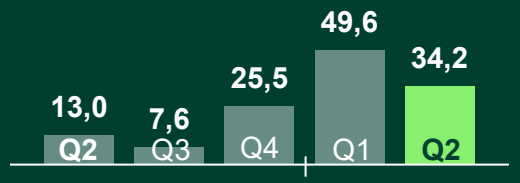
Gross profit margin by quarters

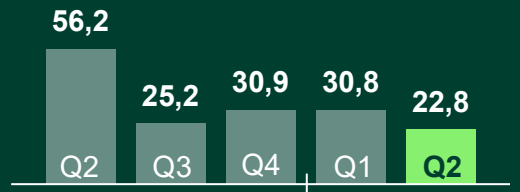


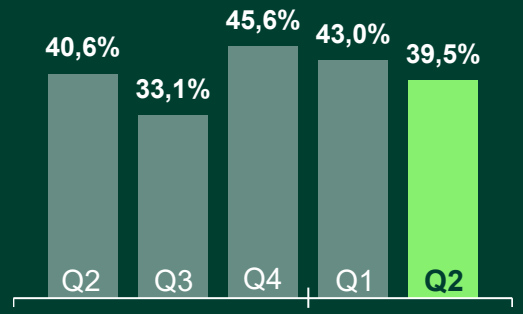
EBIT margin by quarters

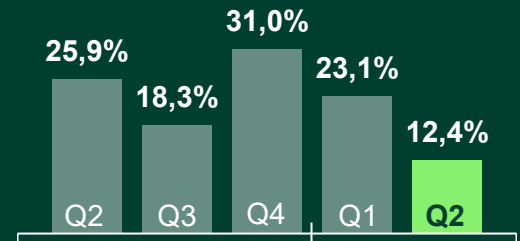


Photomask Solutions









The prior-year figures have been adjusted.

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Transition year 2026: A temporary dip in sales is expected, leading to lower fixed-cost coverage and, together with rising R&D expenses, to a lower EBIT margin while the gross profit margin remains broadly stable

Guidance 2026

(as of March 30, 2026)

Sales
in € million

425–485

Actual 2025:
€ 503.2 million

Gross profit margin in %

35–37

Actual 2025:
35.7%

EBIT margin
in %

8–10

Actual 2025:
13.1%

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Market outlook and Ambition 2030



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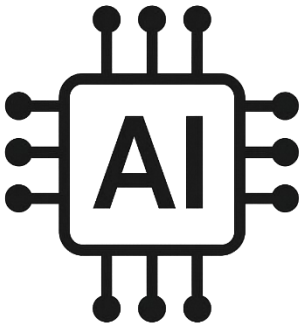
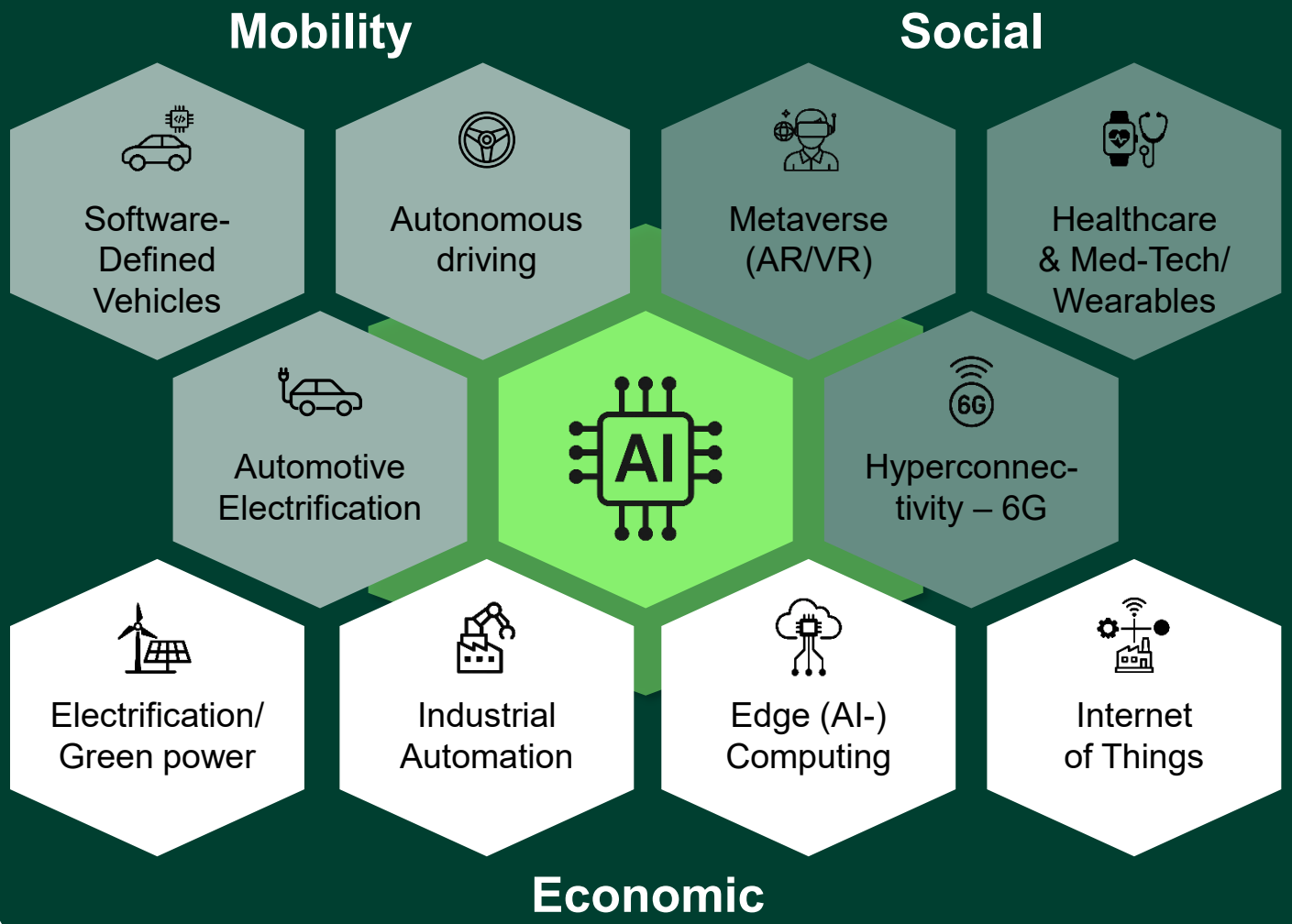


Today's tech trends, accelerated by AI, are built on semiconductors

Fueling rapid growth across the semiconductor ecosystem



Trend Selection – not exhaustive

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SUSS long term ambitions for 2030

€ 750 – 900 m

Sales
SUSS Ambition 2030

~ 8 –12% annual sales growth
compared to 2025

43 – 45%

Gross profit margin
SUSS Ambition 2030

+ ~8%-points GP margin
expansion compared to 2025

20 – 22%

EBIT margin
SUSS Ambition 2030

+ ~8%-points EBIT margin
expansion compared to 2025



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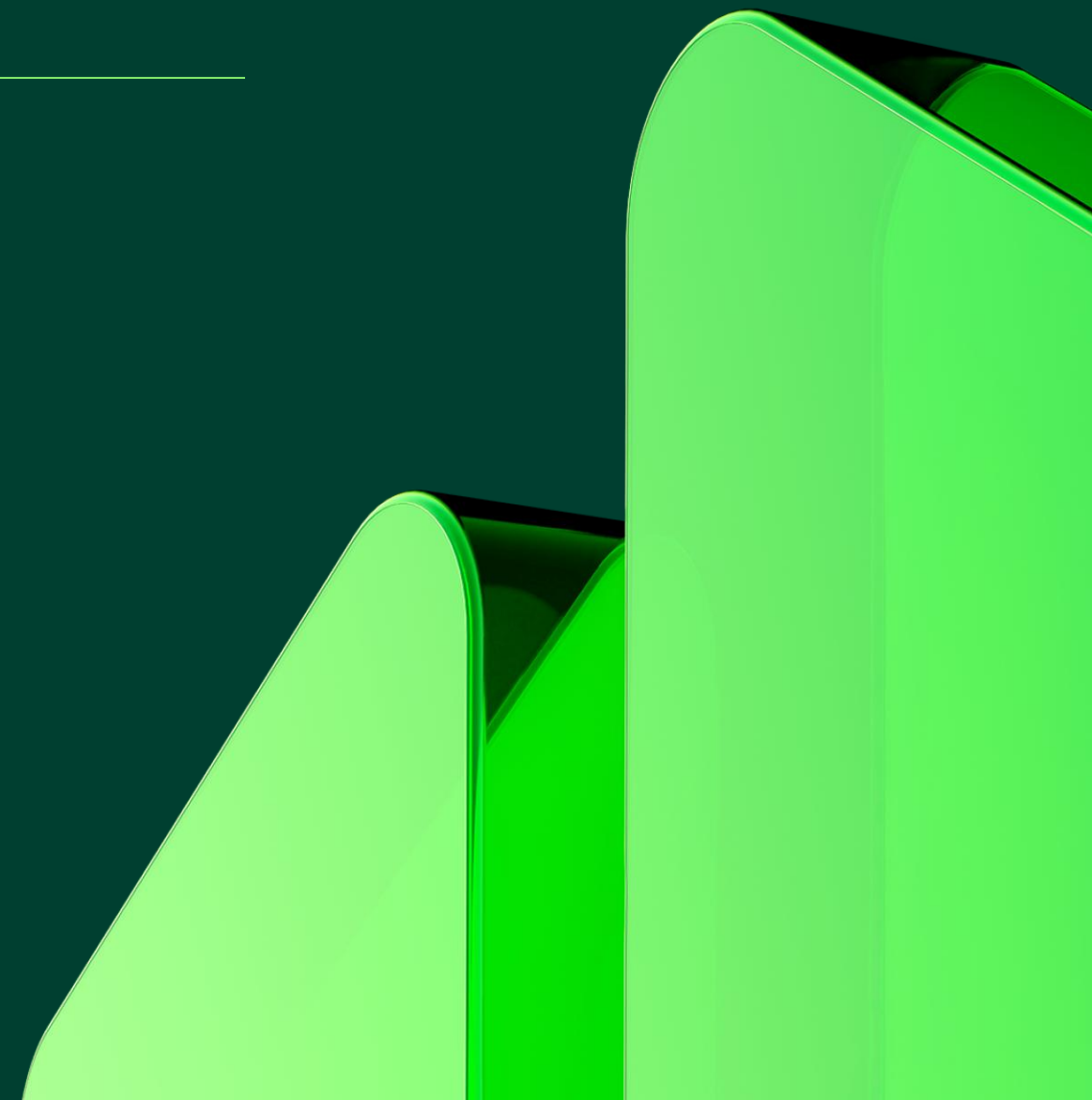
Q&A



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Investor Relations information

Conference and Roadshow Calendar

August 11, 2026
mwb Virtual Round Table

August 19/20, 2026
Needham Virtual Semiconductor Conference | Virtual

August 24, 2026
Jefferies Semiconductor & Tech Conference | Chicago

August 26, 2026
db Global Technology Conference | Dana Point

September 21, 2026
Berenberg/Goldman Sachs German Corporate Conf. | Munich

There may be changes to the SUSS conference and roadshow schedule.

Financial Calendar

August 6, 2026
Half-yearly financial Report

November 5, 2026
Quarterly Statement Q3 2026

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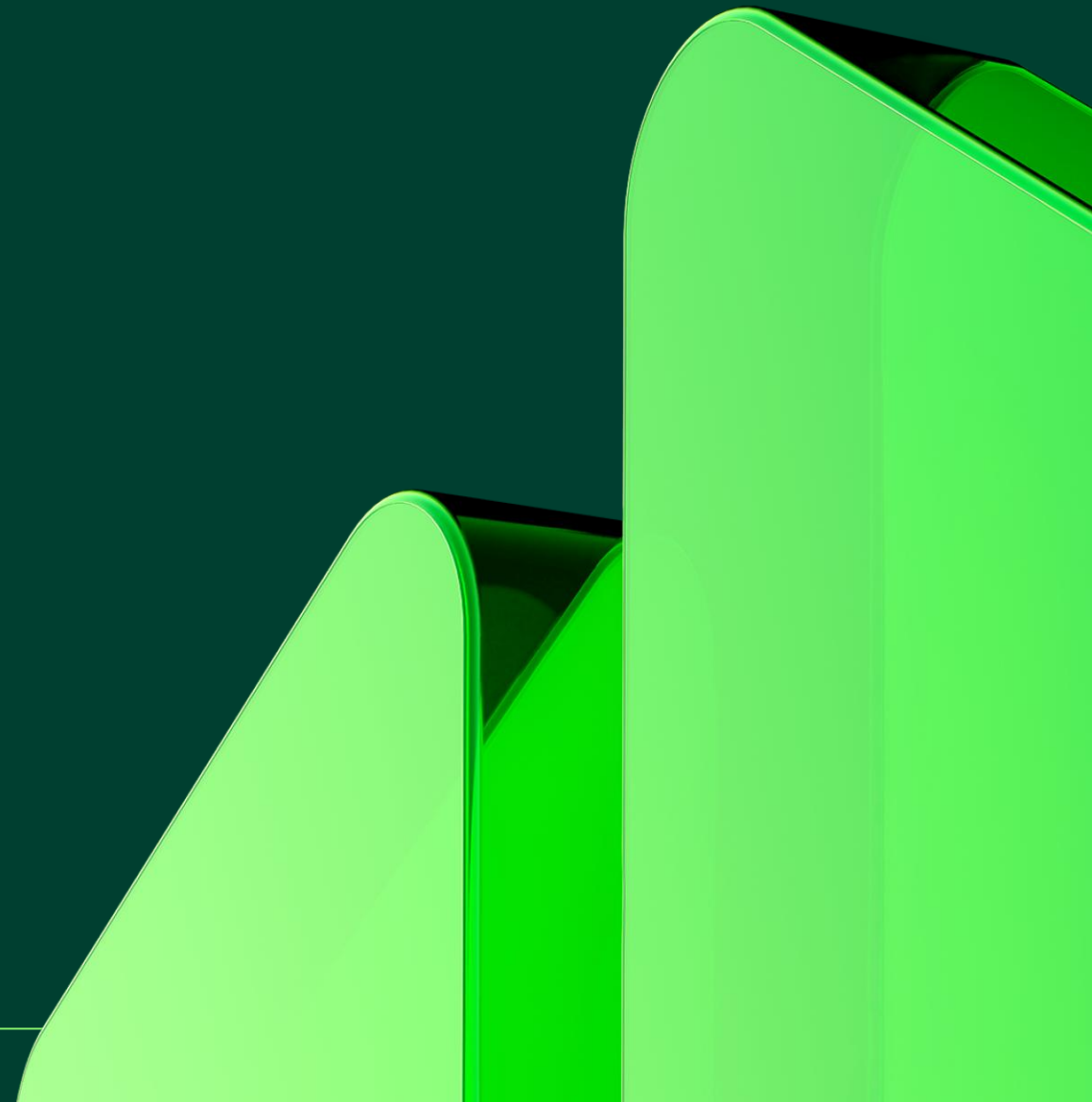
Disclaimer

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec SE and its subsidiaries and associates.

Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec SE. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements.

SUSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.



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Thank you

Growing Innovation



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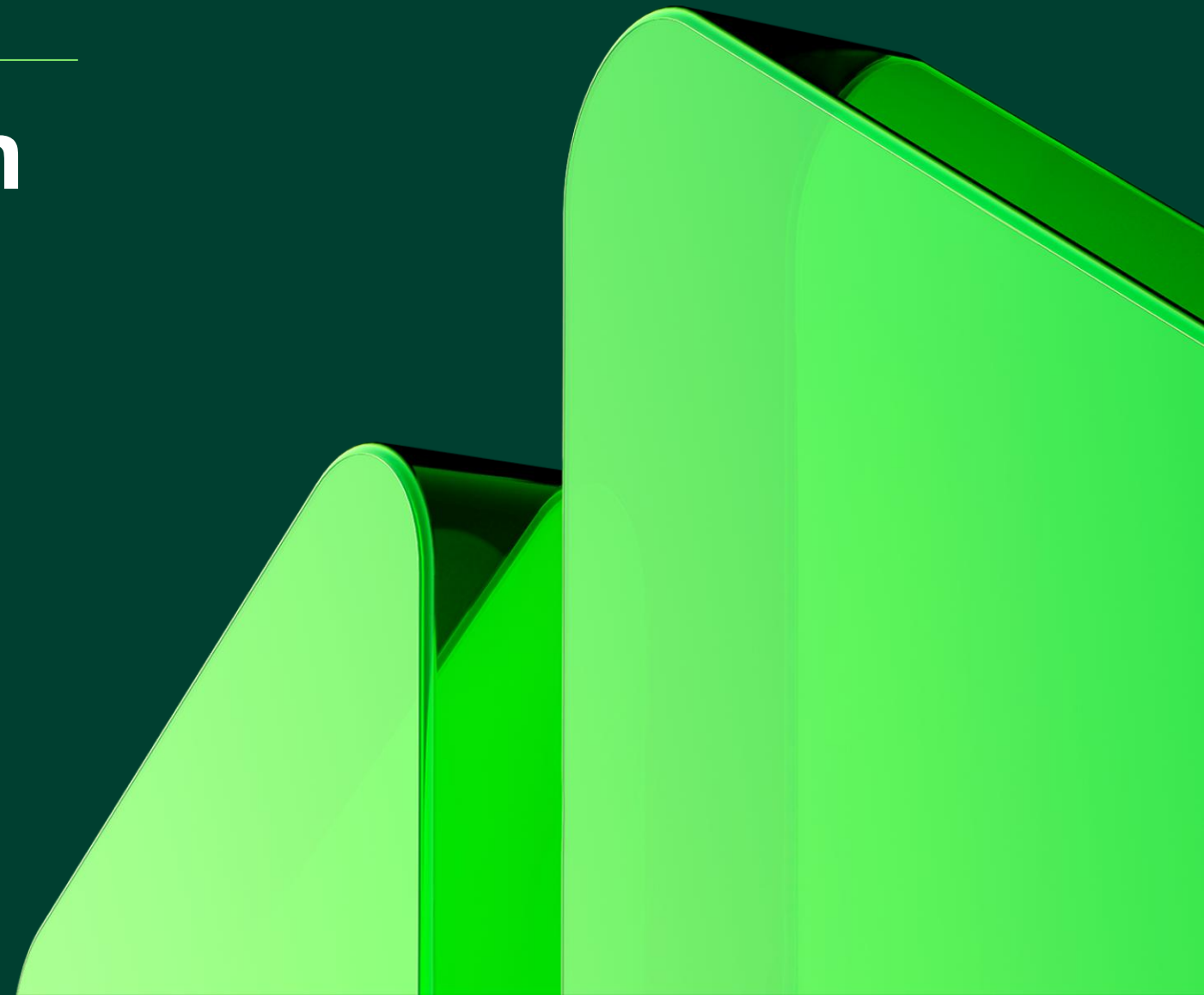
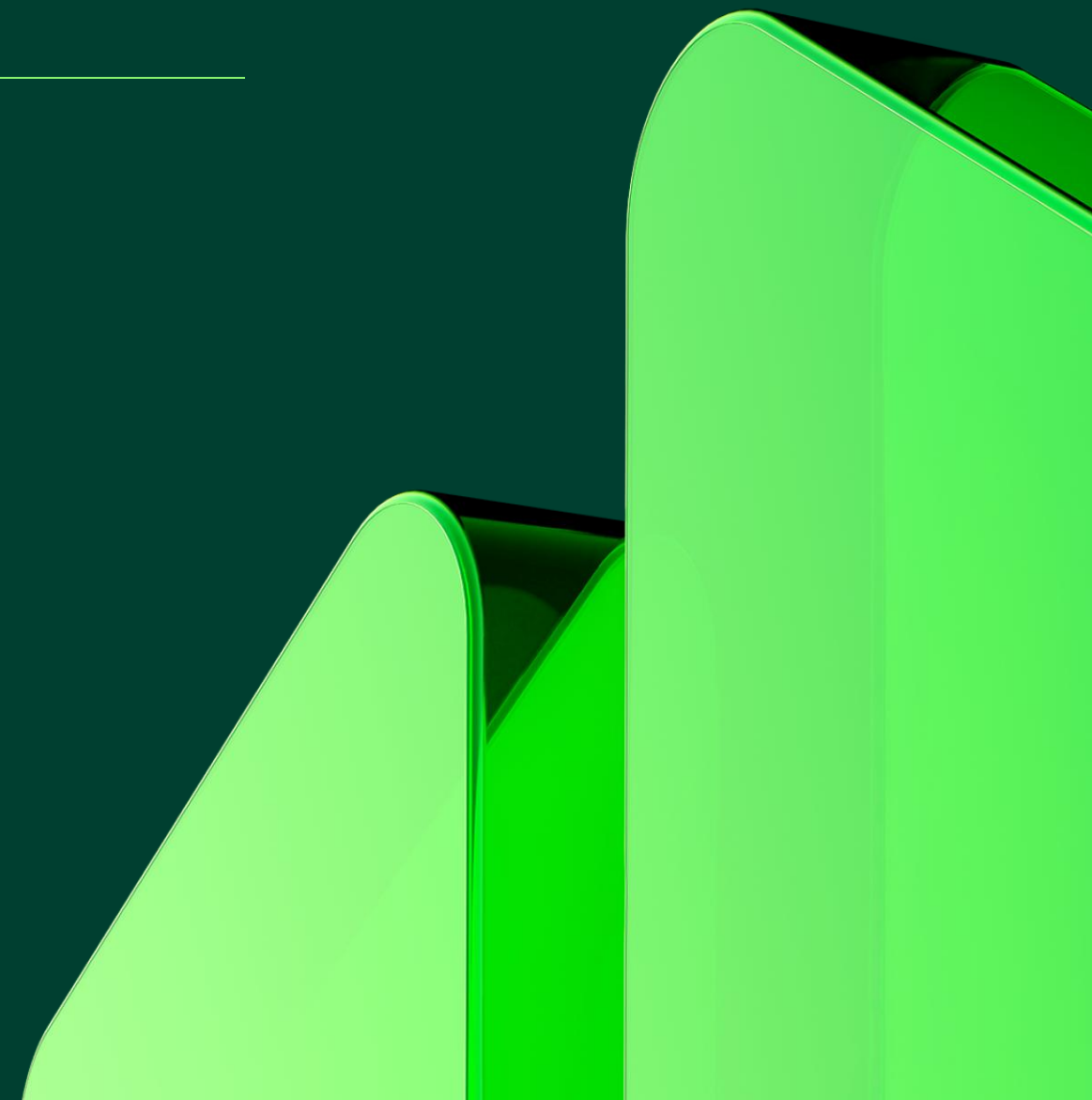


August 11, 2026

Appendix



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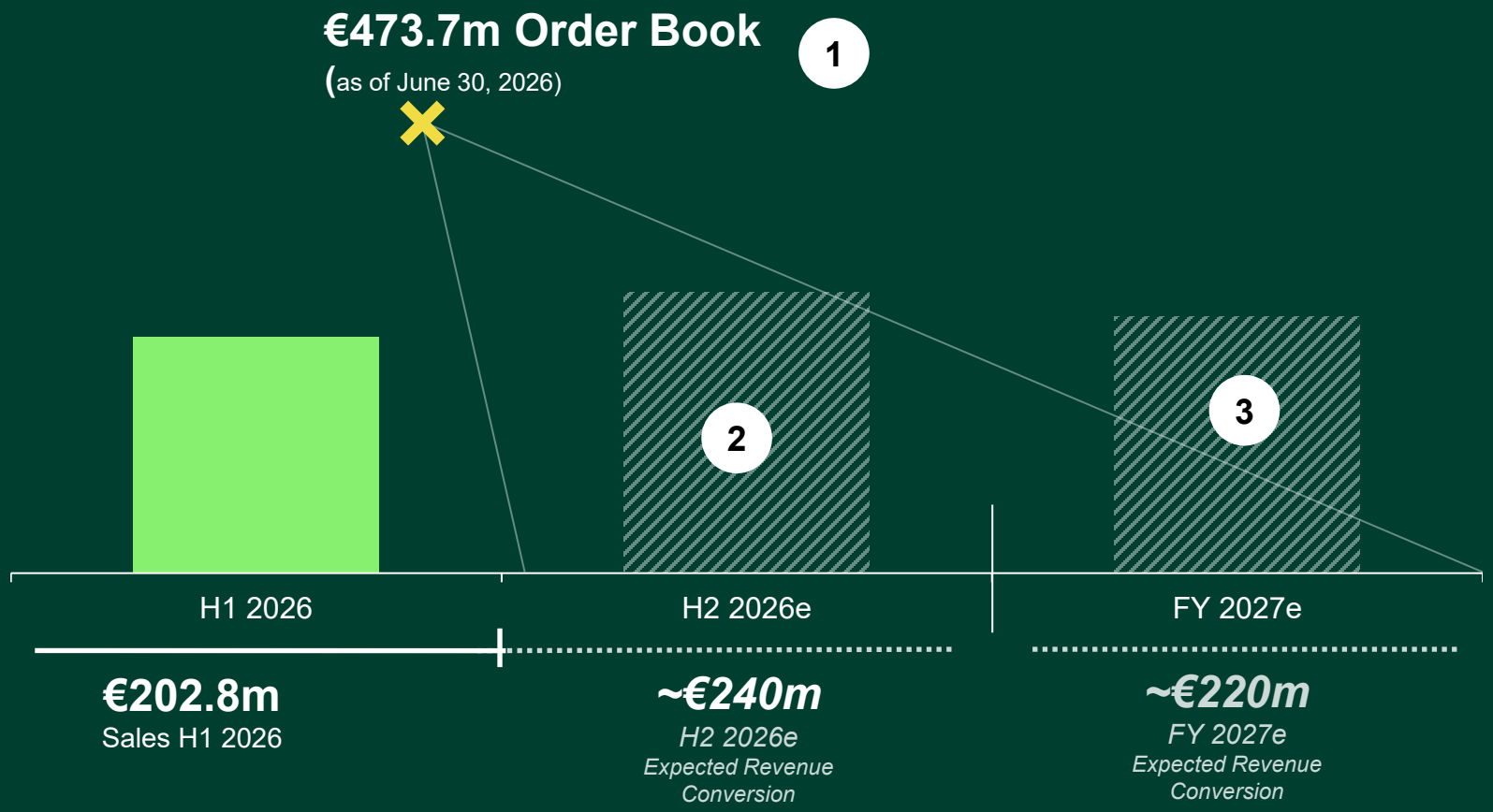
Order Book:
Strong Order Intake improves visibility for 2027 significantly



1. Order Book as of June 30, 2026, increases to **new all-time high** of €473.7m
2. Out of the current Order Book, **~€240m** are expected to convert into sales in 2026
3. **Visibility for 2027 improves** with ~€220m of orders already planned for the fiscal year ahead*

** The expected revenue conversion reflects the current order book and planned delivery schedules as of June 30, 2026. It does not represent management guidance or a revenue forecast.*

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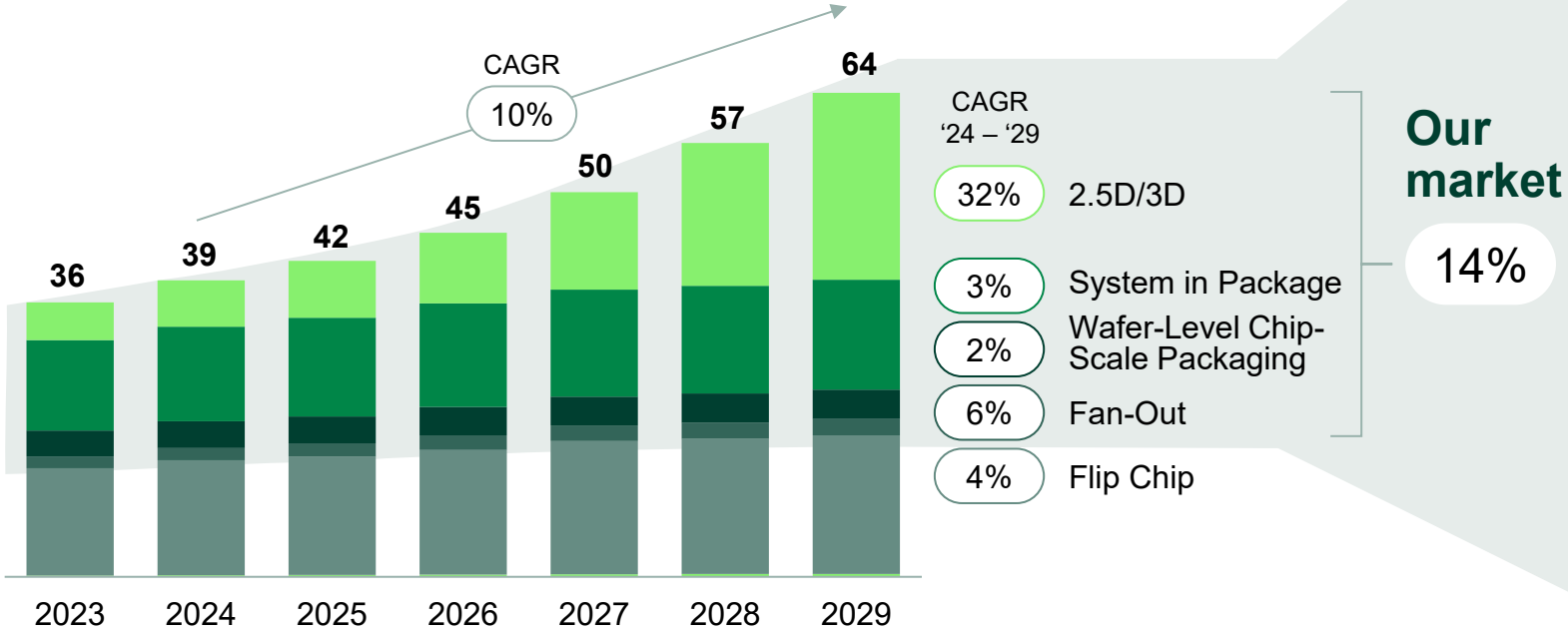
Advanced Packaging | Strong growth ahead – largely fueled by 2.5D and 3D packaging

As demand for high-performance computing rises, the **value in Advanced Packaging is shifting** toward high-end technologies

Advanced Packaging forecast [Million Wafer/Year]



XX% CAGR '24 – '29

Source: Yole (2024)

Interconnection of chips, wafers, and interposers (e.g., Redistribution Layers, Through-Interposer Via, Micro Bumps)

- Patterning with our Lithography equipment: (Coater & Developer, Exposure equipment)

Structural support for thin elements

- Temporary bonding on carrier wafer with our temporary bonding/de-bonding equipment

Mounting dies onto other dies or interposers

- Interposer stacking and die attach/ stacking with our permanent bonding equipment (incl. Hybrid Bonding)

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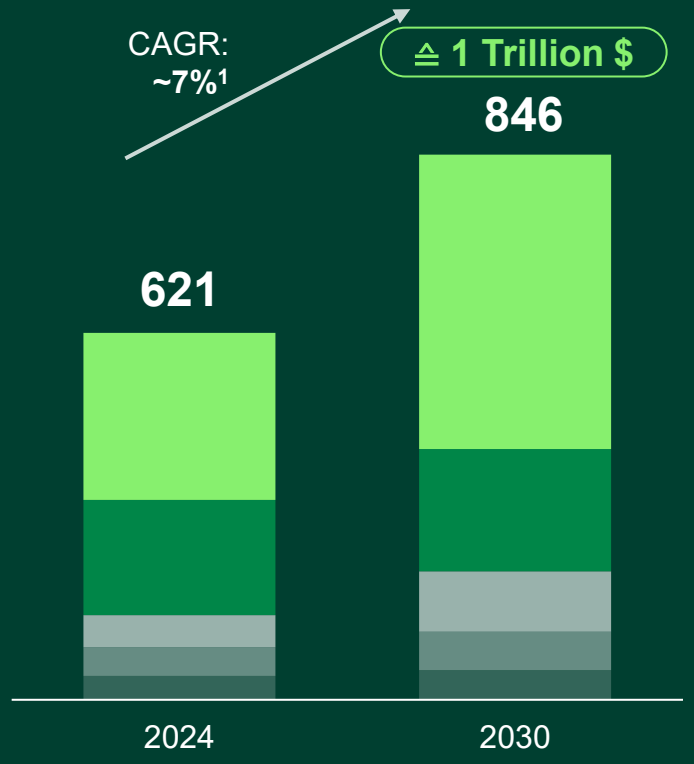
AI-led secular trends are driving semiconductors toward a $1 trillion market by 2030

Semiconductor device revenue forecast (€bn) & key growth driver



Market segment	Growth-drivers	
Computing & Data Storage	**AI** (Generative-, Agentic-, Physical-AI)	Key growth driver
	Autonomous driving	
	Industrial Automation / Internet of Things	
	Metaverse (AR/VR)	
Communications	Hyperconnectivity – 6G	
Automotive	Software-Defined Vehicles / Autonom. driving	
	Automotive Electrification	
Industrial	Industrial Automation / Internet of Things	
	Electrification / Green power generation	
Consumer	Metaverse (AR/VR)	
	Healthcare Wearables	

[1] Based on USD values
Source: SUSS Research; market size based on Yole (2025); Note: USD/EUR forward exchange rate = 1.18, USD/EUR 2024 exchange rate = 1.08, Trend Selection – not exhaustive

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Rising application requirements are blurring the lines between Frontend & Backend territories – addressed in our Business Unit strategy

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Frontend

Node size mitigation: Moore's Law continues with nodes shrinking toward Ångström era

Backend

Advanced Packaging: evolution & broad adoption of heterogeneous chiplet technology

Higher accuracy & cleanliness driving customer demands closer to frontend standards

Efficient & green processes:
Growing customer demand for reduced material usage and environmentally sustainable materials

Photomask Solutions	**Photomask Cleaning, Bake & Develop**	**Wafer Cleaning**
Advanced Backend Solutions		**Bonding, Coating & Imaging**

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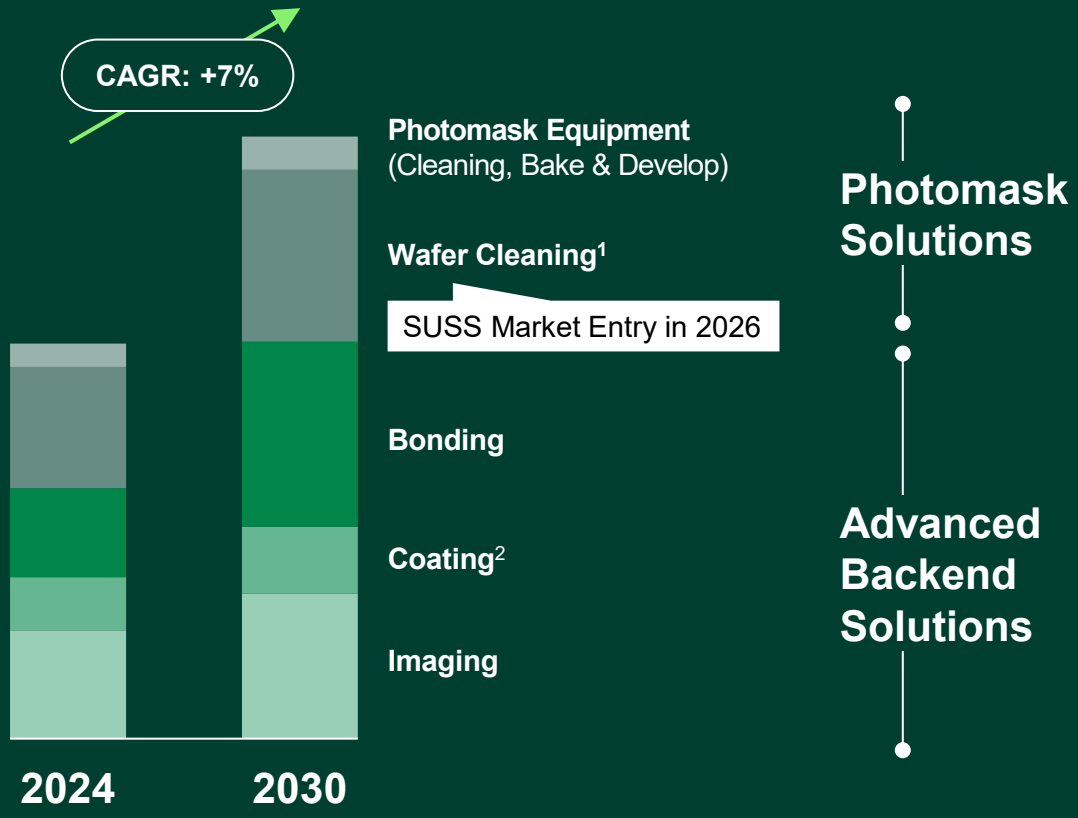
Serviceable market is expected to grow by ~7% per annum through 2030

Serviceable Available Market (Revenue in €M)



[1] MEMS, Power, CIS & Advanced Packaging market reflected; [2] Only Backend Coating market; Inkjet: Upside from expanding into additive manufacturing not reflected | Source: SUSS Research, primarily based on Yole

Photomask Equipment

- **High-End mask market leading growth**
- Mid-End mask market growing mid-to high single digits annually

Wafer Cleaning

- **Market entry with MEMS, Power & CMOS Image Sensors;** Expansion into Advanced Packaging with 300 mm tool planned (tool launch in 2027)
- Memory – future upside (not in market size reflected)

Bonding

- **Temporary Bonding** will **continue to grow** especially driven by high demand for AI
- **Hybrid Bonding with strong growth** ahead driven by advanced Logic & Memory

Coating

- **Advanced Packaging drives growth** in Backend Coating segment
- **Inkjet offers upside beyond traditional coating**, expanding into additive manufacturing

Imaging

- **Advanced Packaging fuels growth;** larger reticle-size dies supports adoption of full-field projection scanning

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Upcoming new product introductions – initiating next growth phase

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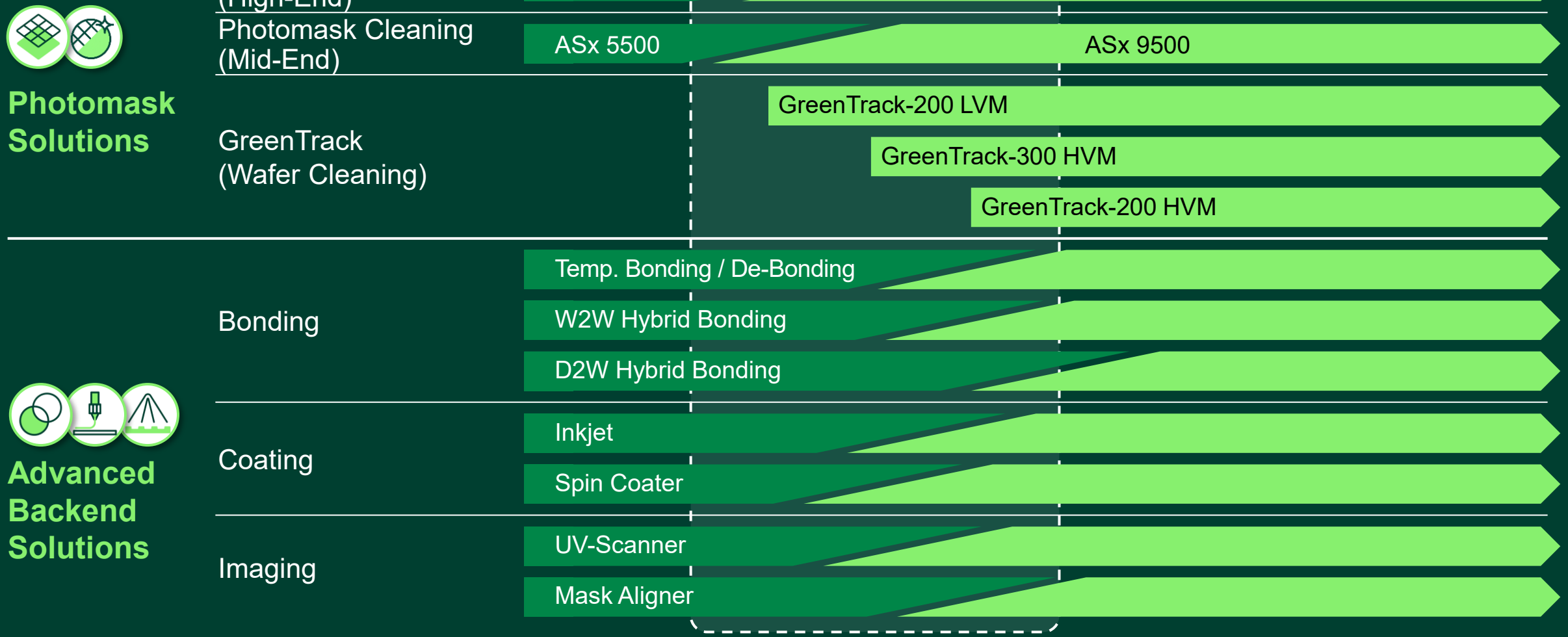

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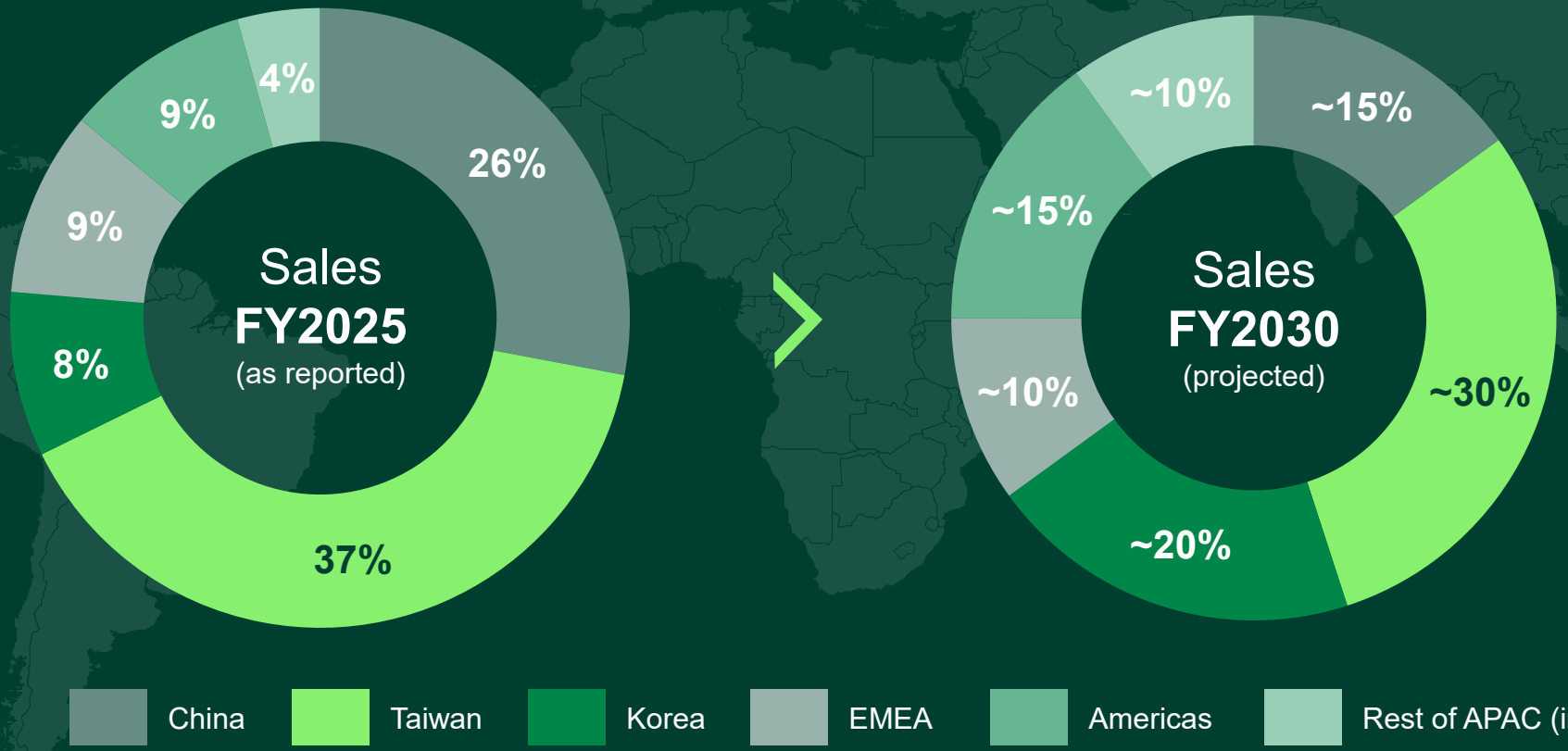
More diversified regional growth – with normalizing China share



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SUSS – a valued partner in the semi ecosystem – Working alongside leading chip companies, as well as key research and industrial partners

We have expanded our global standing

and have become a valued part of the semi ecosystem.

Our key success factors are:

- Focusing on market leaders
- Engaging into commercial and technology partnerships
- Creating customer intimacy through joint process development and key account management
- Local presence with highly qualified customer service and application support

Foundries and OSATs	Integrated Device Manufacturers (IDMs)	Technology and material partners	Academia, consortia and institutes
tsmc	micron	set	imec
Amkor Technology	SAMSUNG	brewer science	cea leti
ASE	SK hynix	Nissan Chemical CORPORATION	semi [1]
	intel	ShinEtsu	Fraunhofer
	infineon	EPSON	TUM
	ST	micro resist technology	KIT
	onsemi	CORNING	TEXAS INSTITUTE FOR ELECTRONICS
	Wolfspeed	SCHOTT	bridg
	Texas Instruments		Georgia Tech

[1] 3DIC Advanced Manufacturing Alliance

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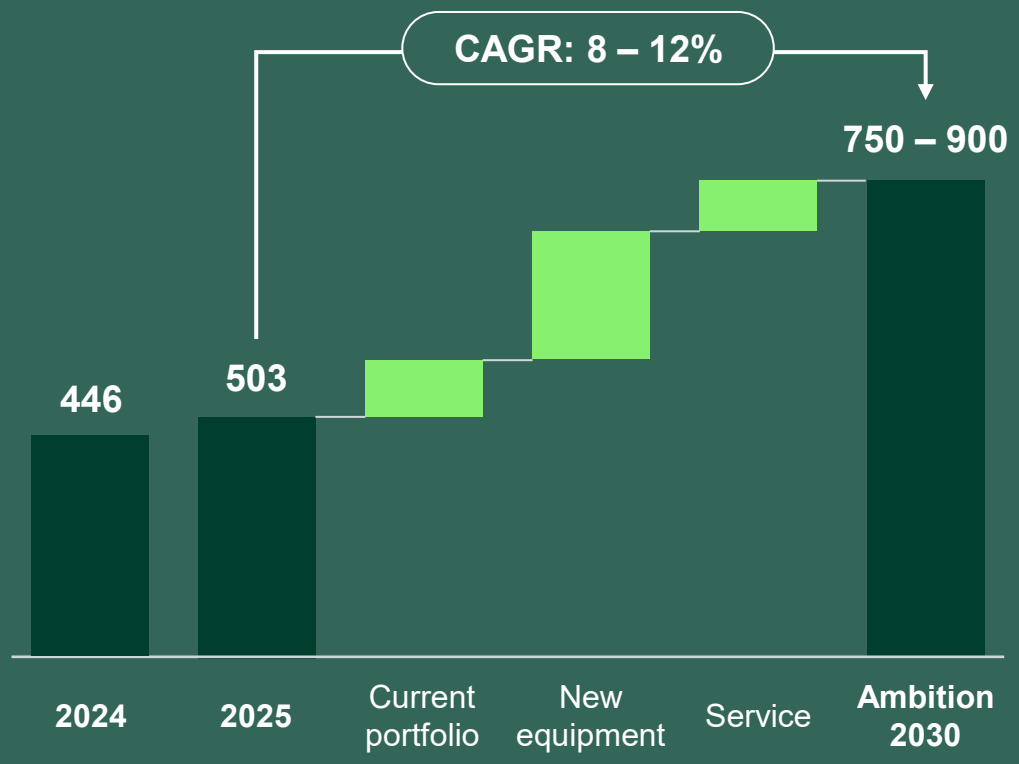
Group growth based on strong evolving portfolio, new product introductions, and a strengthened service business

Revenue development (in €M)



Current portfolio – key revenue drivers:

Photomask Equipment	Remain #1 in high-end segment and expand leadership into mid-end segment
Temporary Bonding	Sustaining leadership – especially in the HBM market segment
UV-Scanner	Expand footprint in Advanced Packaging, leveraging strong position at the #1 foundry

New equipment – key revenue drivers :

Wafer Cleaning	Enter the Wafer cleaning market with an innovative, cost-efficient & green solution
Hybrid Bonding	Entry into Advanced Logic and HBM market, enabled by excellent technological performance
Inkjet Coating	Shaping Inkjet market – a cost-efficient Coating solution and enabler for Additive Manufacturing

Service – key revenue drivers:

Growing Service revenue share from 18% to 25%, with Service now a strategic business contributor

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Growth path underpinned by AI-driven market tailwind and continued expansion into new segments

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2025 - 2030

8 – 12% sales growth p.a.

=

Tool sales

Growth Driver	*Growth Impact*
Market growth	High
+	
New market entry[1]	High
+	
Market share expansion	Moderate
+	
Service	Intermediate

1) Wafer Cleaning & Hybrid Bonding

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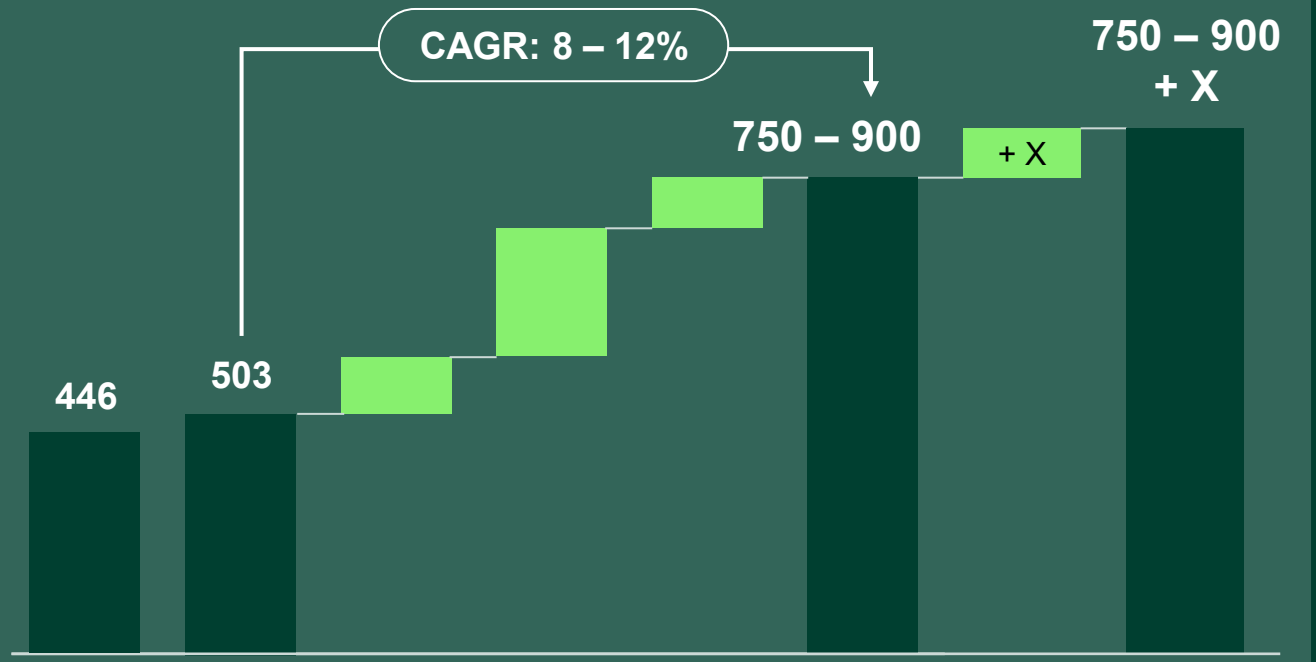
Active pursuit of inorganic growth – we have the means and are looking for the right fit

Revenue development (in €M)



Strategically enhancement of existing portfolio

- Acquisition must support existing strategic priorities, not merely broaden the portfolio
- Acquisition should not structurally dilute our margin
- Carve out and integration efforts need to be manageable – culturally, operationally, and organizationally

Acquisition of Know-How to accelerate product development

- In-house development not feasible, or significant time savings achievable through acquisition
- Clear path to monetization must be visible

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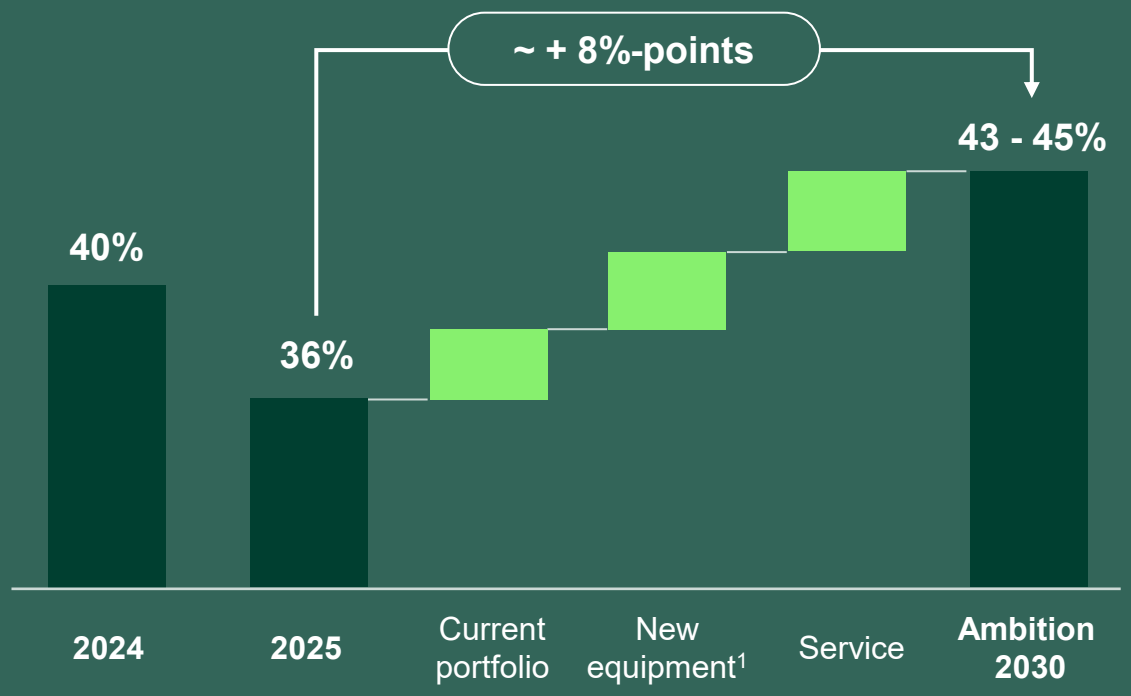
Balanced margin expansion driven by the existing portfolio, new equipment platforms, and service

Gross profit margin development (in %)



1) Wafer Cleaning, Hybrid Bonding & Inkjet

Current (evolving) portfolio:

- New modular & standardized product generations (e.g. new Mask Cleaner, UV-Scanner & Mask Aligner)
- Optimized production network & further improved capacity utilization

New equipment:

New products with higher margins than the current portfolio due to new equipment design (exception: Hybrid Bonder, where the die-bonding module is sourced externally)

Service:

Overall margin improvement through more strategic installed base management and focused service product portfolio

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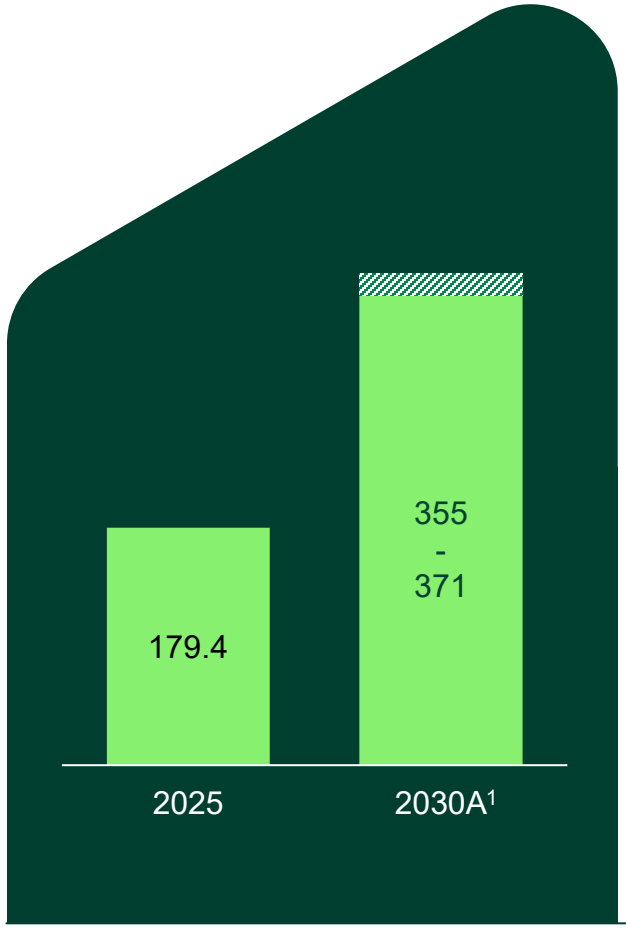
EBIT margin to benefit from higher business volume while increased R&D spend is covered by decline of SG&A expense ratio

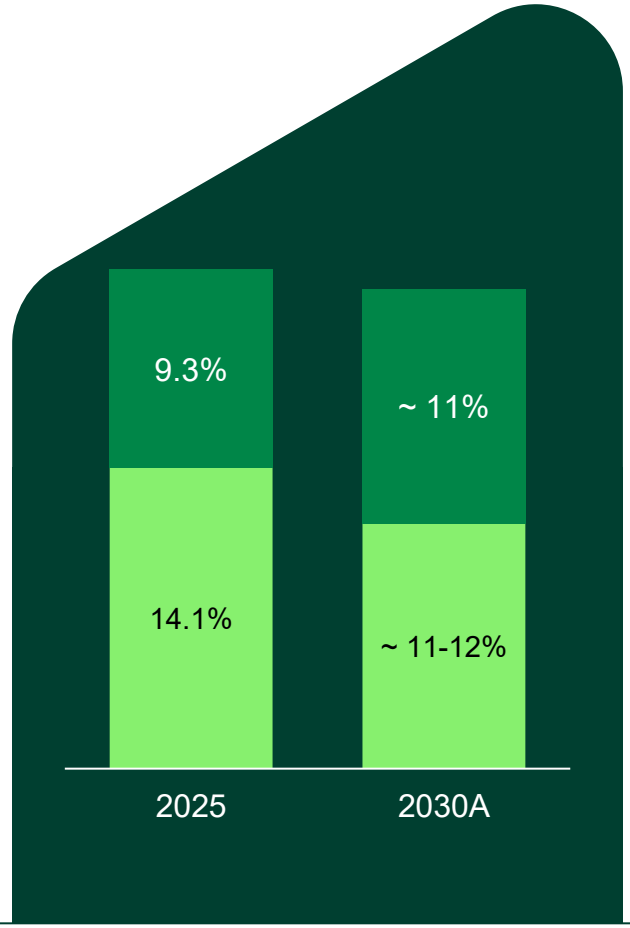
How to achieve the targeted EBIT margin of 20 – 22%



Benefiting from increase in gross profit

Gross profit has the potential to **~ double** from 2025 to 2030, driven by larger business volume with improved profitability

[1] Gross profit is calculated based on the mid-point of the 2030 sales ambition.



Reduced SG&A expense ratio projected

- **R&D expense ratio** is expected to increase to support sales growth
- **SG&A expense ratio** is expected to decrease by ~ 2 to 3 %-points due to below-average increase in selling costs and admin functions

R&D expense ratio

SG&A expense ratio

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Our ambition is to take SUSS to a new financial level by 2030

	FY 2025	FY 2030A
Sales	€503.2 million	€750 – 900 million
Sales growth	12.6% (YoY)	8 to 12% (CAGR 2025 – 2030A)
Gross profit margin (in %)	35.7%	43 to 45%
SG&A (in % of sales)	14.1%	~11 to 12%
R&D (in % of sales)	9.3%	~11%
EBIT margin (in %)	13.1%	20 to 22%
Free Cashflow (continuing operations)	€-22.6 million	~ €90 million
ROCE	21.3%	39 to 41%
CapEx	€23.2 million	~ €22 million (annual ⌀ 2026 – 2030)
Tax rate	24.6%	~28%[1]

[1] The internal planning assumption for the tax rate is generally ~ 28%.

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SUSS hybrid bonding solutions – understanding customer's needs



Wafer-to-wafer HB
XBS300 W2W

Product launched: 10/2022
Target customers: HVM



Die-to-wafer/wafer-to-wafer HB
XBC300 Gen2 D2W/W2W

Product launched: 05/2024
Target customers: Research institutes, R&D teams of HVM



Die-to-wafer HB
XBC300 Gen2 D2W

Product launched: 5/2025
Target customers: HVM

We optimize our product solutions to serve our customer's device and manufacturing needs.

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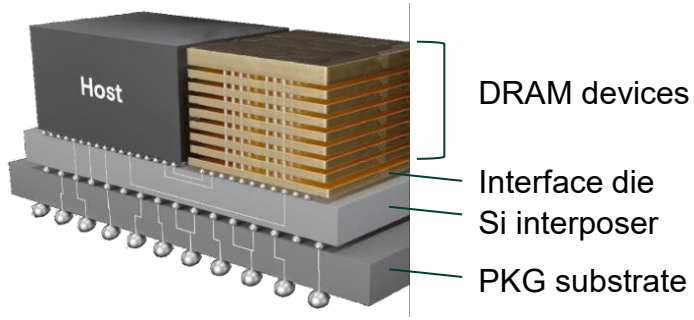
HBM roadmap enables SUSS to grow in existing and new markets

	HBM3E	HBM4	HBM4E	HBM5
Expected SOP	2024	2026	2026 or 2027	2027 or 2028
# of DRAM layer acc. to JEDEC	8/12	12	16	16/20
Bonding type in DRAM stack	TCB	TCB	TCB and HB	TCB and HB
Thinning of DRAM devices	TBDB	TBDB	TBDB	TBDB



source: Micron, HBM3E

Relevance for SUSS:

1. TBDB remains a crucial process for thinning of DRAM devices used in HBM cube
   Growth of existing SUSS TBDB business in line with general HBM market growth
2. Increase of layer number in HBM cube triggers more TBDB capacity for thinning of DRAM devices
   Additional growth of SUSS TBDB business in line with higher layer in HBM cube
3. Hybrid bonding will gradually replace Thermal Compression bonding for stacking of DRAM devices
   Expansion into this market offers new growth opportunities with SUSS HB solutions

TCB: Thermal compression bonding, HB: hybrid bonding, TBDB: Temporary bonding & de-bonding

© SUSS

2.5/3D Chiplet Technology | SUSS well positioned to benefit from the strong momentum in 2.5D and 3D evolution

Temporary Bonding
- **HBM:** Structural support during thinning

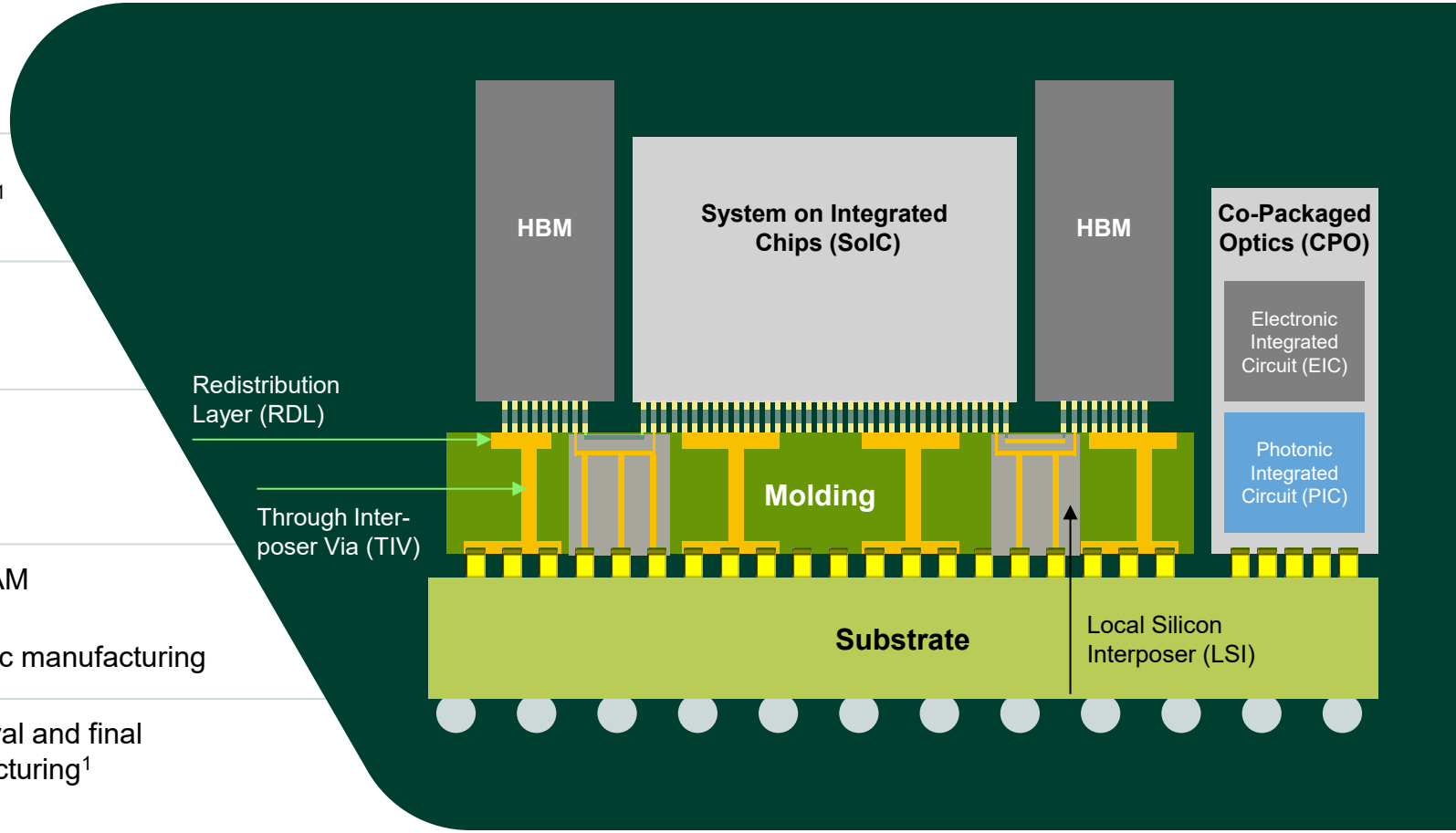
Hybrid Bonding
- **HBM:** Stacking of DRAMs[1]
- **CPO:** Stacking of PIC & EIC[1]
- **SoIC:** E.g., Logic-on-Logic[1]

Inkjet-/ Spin Coating
- **TIV:** Lithography
- **RDL:** Lithography[1]

UV-Scanner (Exposure)
- **TIV:** Lithography
- **RDL:** Lithography[1]

Photomask Cleaning (Frontend)
- **HBM:** Mask Cleaning in DRAM manufacturing
- **SoIC:** Mask Cleaning in Logic manufacturing

Wafer Cleaning
- **HBM:** Critical material removal and final cleaning in Backend manufacturing[1]



[1] Potential future use case

BU Advanced Backend Solutions

BU Photomask Solutions

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Our three manufacturing sites for semiconductor equipment

	 **Garching** HQ, Germany	 **Sternenfels** Germany	 **Hsinchu/Zhubei** Taiwan
Photomask Cleaning		 MaskTrack X	
Bonding Systems		 XBC300	 XBS300
Coating Systems			 ACS300
Imaging Systems	 Mask Aligner MA200/300		 UV Projection Scanner DSC300
Operations employees 2025	**48**	**176**	**175**

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